

SMT870-23

TECHNICAL DATA

Infrared LED, SMD

SMT870-23 is a AlGaAs LED, mounted on a lead frame as TOP LED package with plastic ball lens. On forward bias, it emits a radiation of typical 22 mW at a peak wavelength of 870 nm.

Specifications

Structure: AlGaAs cathode mark Peak Wavelength: 870 nm **Optical Output Power:** 22 mW SMD, PPA resin Package: Lead frame die: silver plated .5±0. 2±0. Lens: epoxy resin (Ø2.6 mm) Absolute Maximum Ratings ($T_A=25^{\circ}C$) $7 \pm 0.$ 1.7 Symbol Value Unit Item 2.2 ± 0.1 Power Dissipation P_D 160 mW 3.5 Forward Current 100 I_{F} mΑ Pulse Forward Current * 1000 mΑ I_{FP} **Reverse Voltage** 5 V_R V Junction Temperature ΤJ 100 °С Thermal Resistance 190 K/W R_{thia}

-20 ... +80

-30 ... +80

255

°С

°C

°C

(Unit: mm)

0 20

4

AlGaAs

T_{sol} *1 duty = 1%, pulse width = 10 µs

Operating Temperature

Soldering Temperature *2

Storage Temperature

*² must be completed within 3 seconds at 260°C

T_{opr}

T_{sta}

Electro-Optical Characteristics

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	V _F	I _F = 50 mA	-	1.45	1.60	V
Pulse Forward Voltage	V _{FP}	$I_{FP} = 100 \text{mA}, t_P = 20 \text{ms}$	-	1.50	1.80	V
Reverse Current	I _R	$V_R = 5 V$	-	-	10	μA
Total Radiated Power	Po	I _F = 50 mA	16	22	-	mW
		$I_{FP} = 100 \text{mA}, t_P = 20 \text{ms}$	-	44	-	
Radiant Intensity	Ι _Ε	I _F = 50 mA	-	40	-	mW/sr
		$I_{FP} = 100 \text{mA}, t_P = 20 \text{ms}$	-	80	-	
Peak Wavelength	λ _P	I _F = 50 mA	855	870	885	nm
Half Width	Δλ	I _F = 50 mA	-	40	-	nm
Viewing Half Angle	$\Theta_{1/2}$	I _F = 50 mA	-	±15	-	deg.
Rise Time	t _r	I _F = 50 mA	-	15	-	ns
Fall Time	t _f	I _F = 50 mA	-	10	-	ns

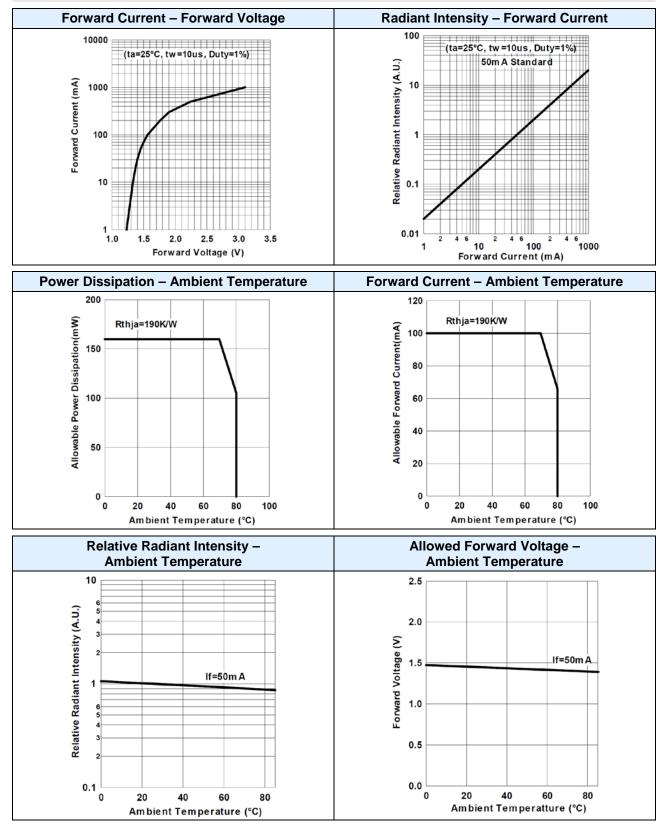
Radiated Power is measured by Photodyne #500

Radiant Intensity is measured by Tektronix J-6512

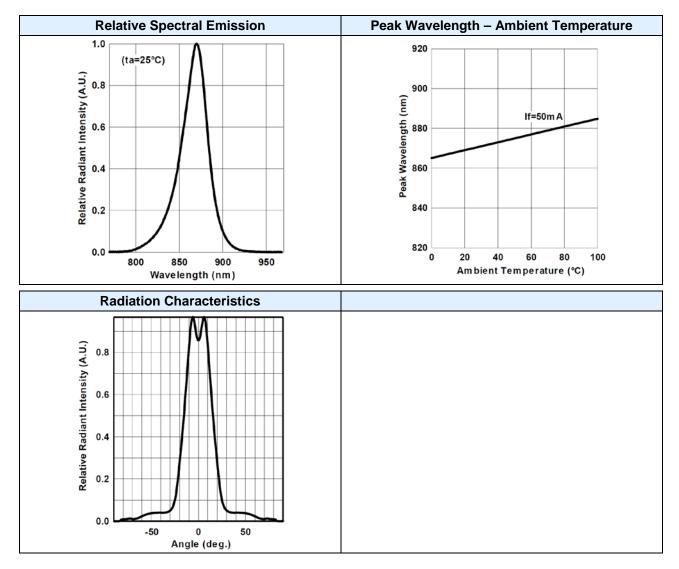
Note: The above specifications are for reference purpose only and subjected to change without prior notice.



Typical Performance Curves









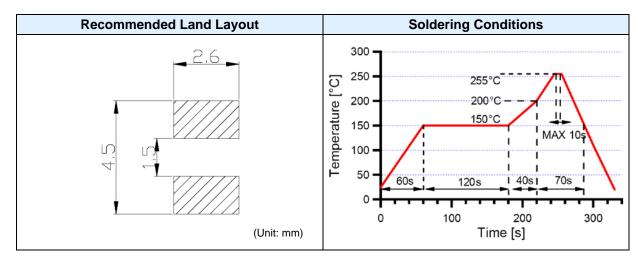
Precaution for Use

1. Cautions

- DO NOT look directly into the emitting area of the LED during operation!
- WARNING: LED is emitting invisible light!

2. Soldering Conditions

- DO NOT apply any stress to the lead particularly when heat.
- After soldering the LEDs should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.



3. Static Electricity

- The LEDs are very sensitive to Static Electricity and surge voltage. So it is recommended that a wrist band and/or an anti-electrostatic glove be used when handling the LEDs.
- All devices, equipment and machinery must be grounded properly. It is recommended that precautions should be taken against surge voltage to the equipment that mounts the LEDs.



4. Heat Generation

- Thermal design of the end product is of paramount importance. Please consider the heat generation of the LED when making the system design. The coefficient of temperature increase per input electric power is affected by the thermal resistance of the circuit board and density of LED placement on the board, as well as other components. It is necessary to avoid intense heat generation and operate within the maximum ratings given in the specification.
- The operating current should be decided after considering the ambient maximum temperature of LEDs.

5. Storage

- The LEDs should be stored at 30°C or less and 60%RH or less after being shipped and the storage life limits are 3 months. If the LEDs are stored for 3 months or more, they can be stored for a year in a sealed container with nitrogen atmosphere and moisture absorbent material at less than 30%RH.
- Please avoid rapid transitions in ambient temperature, especially in high humidity environments where condensation can occur.